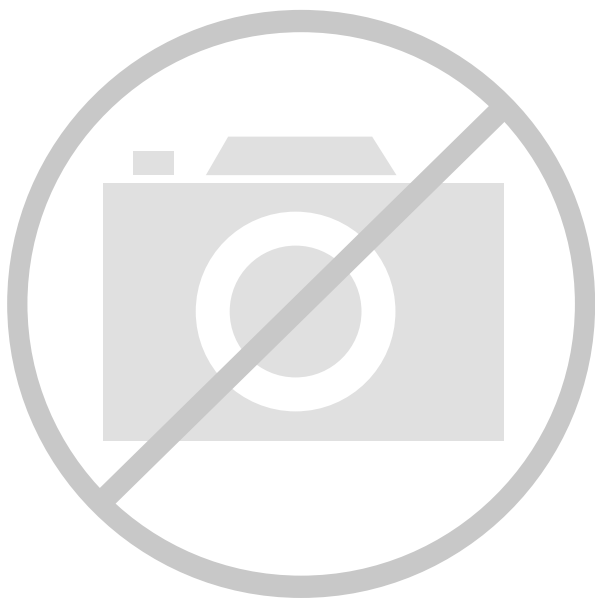




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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	4224
Number of Logic Elements/Cells	-
Total RAM Bits	55296
Number of I/O	248
Number of Gates	250000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	484-BGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax250-1fgg484i

The SRAM blocks are arranged in a column on the west side of the tile (Figure 1-6 on page 1-4).

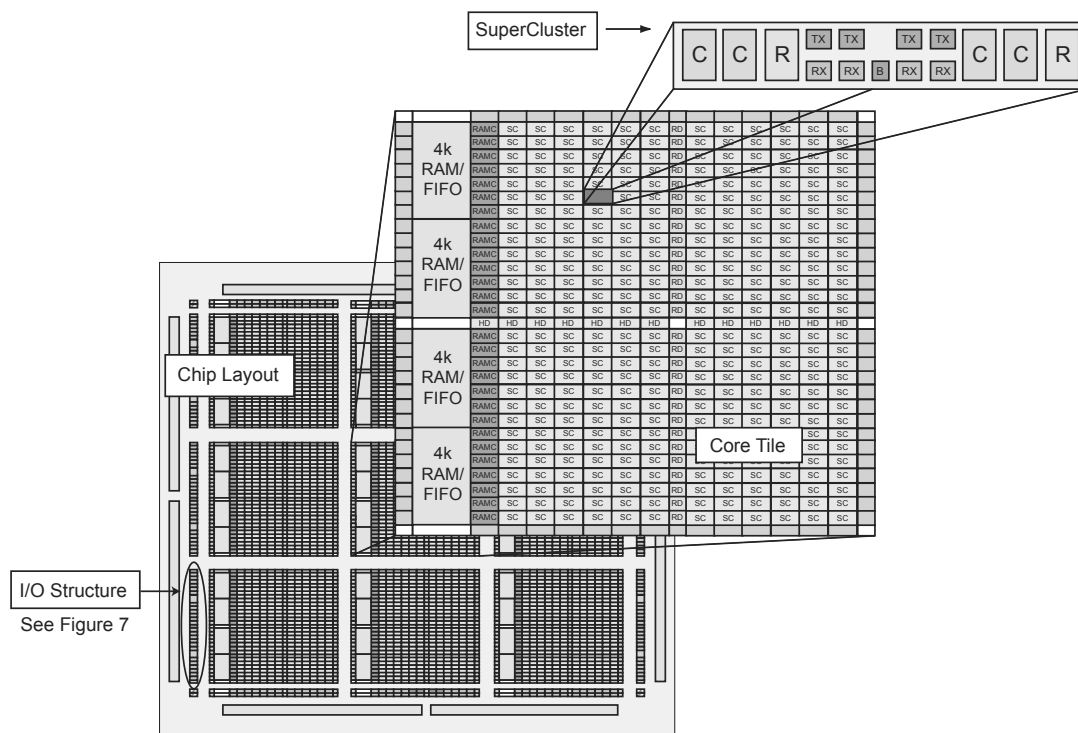


Figure 1-6 • AX Device Architecture (AX1000 shown)

Embedded Memory

As mentioned earlier, each core tile has either three (in a smaller tile) or four (in the regular tile) embedded SRAM blocks along the west side, and each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are: 128x36, 256x18, 512x9, 1kx4, 2kx2 or 4kx1 bits. The individual blocks have separate read and write ports that can be configured with different bit widths on each port. For example, data can be written in by eight and read out by one.

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using core logic modules. The FIFO width and depth are programmable. The FIFO also features programmable ALMOST-EMPTY (AEMPTY) and ALMOST-FULL (AFULL) flags in addition to the normal EMPTY and FULL flags. In addition to the flag logic, the embedded FIFO control unit also contains the counters necessary for the generation of the read and write address pointers as well as control circuitry to prevent metastability and erroneous operation. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

I/O Logic

The Axcelerator family of FPGAs features a flexible I/O structure, supporting a range of mixed voltages with its bank-selectable I/Os: 1.5V, 1.8V, 2.5V, and 3.3V. In all, Axcelerator FPGAs support at least 14 different I/O standards (single-ended, differential, voltage-referenced). The I/Os are organized into banks, with eight banks per device (two per side). The configuration of these banks determines the I/O standards supported (see "User I/Os" on page 2-11 for more information). All I/O standards are available in each bank.

Each I/O module has an input register (InReg), an output register (OutReg), and an enable register (EnReg) (Figure 1-7 on page 1-5). An I/O Cluster includes two I/O modules, four RX modules, two TX modules, and a buffer (B) module.

Thermal Characteristics

Introduction

The temperature variable in Microsemi's Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature. EQ 1 can be used to calculate junction temperature.

$$T_J = \text{Junction Temperature} = \Delta T + T_a$$

EQ 1

Where:

T_a = Ambient Temperature

ΔT = Temperature gradient between junction (silicon) and ambient

$$\Delta T = \theta_{ja} * P$$

EQ 2

Where:

P = Power

θ_{ja} = Junction to ambient of package. θ_{ja} numbers are located under Table 2-6 on page 2-7.

Package Thermal Characteristics

The device junction-to-case thermal characteristic is θ_{jc} , and the junction-to-ambient air characteristic is θ_{ja} . The thermal characteristics for θ_{ja} are shown with two different air flow rates. θ_{jc} values are provided for reference. The absolute maximum junction temperature is 125°C.

The maximum power dissipation allowed for commercial- and industrial-grade devices is a function of θ_{ja} . A sample calculation of the absolute maximum power dissipation allowed for an 896-pin FBGA package at commercial temperature and still air is as follows:

$$\text{Maximum Power Allowed} = \frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}(\text{°C/W})} = \frac{125^{\circ}\text{C} - 70^{\circ}\text{C}}{13.6^{\circ}\text{C/W}} = 4.04 \text{ W}$$

The maximum power dissipation allowed for Military temperature and Mil-Std 883B devices is specified as a function of θ_{jc} .

Table 2-6 • Package Thermal Characteristics

Package Type	Pin Count	θ_{jc}	θ_{ja} Still Air	θ_{ja} 1.0m/s	θ_{ja} 2.5m/s	Units
Chip Scale Package (CSP)	180	N/A	57.8	51.0	50	°C/W
Plastic Quad Flat Pack (PQFP)	208	8.0	26	23.5	20.9	°C/W
Plastic Ball Grid Array (PBGA)	729	2.2	13.7	10.6	9.6	°C/W
Fine Pitch Ball Grid Array (FBGA)	256	3.0	26.6	22.8	21.5	°C/W
Fine Pitch Ball Grid Array (FBGA)	324	3.0	25.8	22.1	20.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	484	3.2	20.5	17.0	15.9	°C/W
Fine Pitch Ball Grid Array (FBGA)	676	3.2	16.4	13.0	12.0	°C/W
Fine Pitch Ball Grid Array (FBGA)	896	2.4	13.6	10.4	9.4	°C/W
Fine Pitch Ball Grid Array (FBGA)	1152	1.8	12.0	8.9	7.9	°C/W
Ceramic Quad Flat Pack (CQFP) ¹	208	2.0	22	19.8	18.0	°C/W
Ceramic Quad Flat Pack (CQFP) ¹	352	2.0	17.9	16.1	14.7	°C/W
Ceramic Column Grid Array (CCGA) ²	624	6.5	8.9	8.5	8	°C/W

Notes:

- θ_{jc} for the 208-pin and 352-pin CQFP refers to the thermal resistance between the junction and the bottom of the package.
- θ_{jc} for the 624-pin CCGA refers to the thermal resistance between the junction and the top surface of the package. Thermal resistance from junction to board (θ_{jb}) for CCGA 624 package is 3.4°C/W.

Timing Characteristics

Axcelerator devices are manufactured in a CMOS process, therefore, device performance varies according to temperature, voltage, and process variations. Minimum timing parameters reflect maximum operating voltage, minimum operating temperature, and best-case processing. Maximum timing parameters reflect minimum operating voltage, maximum operating temperature, and worst-case processing. The derating factors shown in Table 2-7 should be applied to all timing data contained within this datasheet.

Table 2-7 • Temperature and Voltage Timing Derating Factors
(Normalized to Worst-Case Commercial, $T_J = 70^\circ\text{C}$, $V_{CCA} = 1.425\text{V}$)

VCCA	Junction Temperature						
	-55°C	-40°C	0°C	25°C	70°C	85°C	125°C
1.4 V	0.83	0.86	0.91	0.96	1.02	1.05	1.15
1.425 V	0.82	0.84	0.90	0.94	1.00	1.04	1.13
1.5 V	0.78	0.80	0.85	0.89	0.95	0.98	1.07
1.575 V	0.74	0.76	0.81	0.85	0.90	0.94	1.02
1.6 V	0.73	0.75	0.80	0.84	0.89	0.92	1.01

Notes:

- The user can set the junction temperature in Designer software to be any integer value in the range of -55°C to 175°C.
- The user can set the core voltage in Designer software to be any value between 1.4V and 1.6V.

All timing numbers listed in this datasheet represent sample timing characteristics of Axcelerator devices. Actual timing delay values are design-specific and can be derived from the Timer tool in Microsemi's Designer software after place-and-route.

User I/Os²

Introduction

The Axcelerator family features a flexible I/O structure, supporting a range of mixed voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V) with its bank-selectable I/Os. Table 2-8 on page 2-12 contains the I/O standards supported by the Axcelerator family, and Table 2-10 on page 2-12 compares the features of the different I/O standards.

Each I/O provides programmable slew rates, drive strengths, and weak pull-up and weak pull-down circuits. The slew rate setting is effective for both rising and falling edges.

I/O standards, except 3.3 V PCI and 3.3 V PCI-X, are capable of hot insertion. 3.3 V PCI and 3.3 V PCI-X are 5 V tolerant with the aid of an external resistor.

The input buffer has an optional user-configurable delay element. The element can reduce or eliminate the hold time requirement for input signals registered within the I/O cell. The value for the delay is set on a bank-wide basis. Note that the delay WILL be a function of process variations as well as temperature and voltage changes.

Each I/O includes three registers: an input (InReg), an output (OutReg), and an enable register (EnReg). I/Os are organized into banks, and there are eight banks per device—two per side (Figure 2-6 on page 2-18). Each I/O bank has a common VCCI, the supply voltage for its I/Os.

For voltage-referenced I/Os, each bank also has a common reference-voltage bus, VREF. While VREF must have a common voltage for an entire I/O bank, its location is user-selectable. In other words, any user I/O in the bank can be selected to be a VREF.

The location of the VREF pin should be selected according to the following rules:

- Any pin that is assigned as a VREF can control a maximum of eight user I/O pad locations in each direction (16 total maximum) within the same I/O bank.
- I/O pad locations listed as no connects are counted as part of the 16 maximum. In many cases, this leads to fewer than eight user I/O package pins in each direction being controlled by a VREF pin.
- Dedicated I/O pins such as GND and VCCI are counted as part of the 16.
- The two user I/O pads immediately adjacent on each side of the VREF pin (four in total) may only be used as inputs. The exception is when there is a VCCI/GND pair separating the VREF pin and the user I/O pad location.
- The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os.

The differential amplifier supply voltage VCCDA should be connected to 3.3 V.

A user can gain access to the various I/O standards in three ways:

- Instantiate specific library macros that represent the desired specific standard.
- Use generic I/O macros and then use Designer's PinEditor to specify the desired I/O standards (please note that this is not applicable to differential standards).
- A combination of the first two methods.

Refer to the *I/O Features in Axcelerator Family Devices* application note and the *Antifuse Macro Library Guide* for more details.

2. Do not use an external resistor to pull the I/O above V_{CCI} for a higher logic "1" voltage level. The desired higher logic "1" voltage level will be degraded due to a small I/O current, which exists when the I/O is pulled up above V_{CCI} .

5 V Tolerance

There are two schemes to achieve 5 V tolerance:

1. 3.3 V PCI and 3.3 V PCI-X are the only I/O standards that directly allow 5 V tolerance. To implement this, an internal clamp diode between the input pad and the VCCI pad is enabled so that the voltage at the input pin is clamped, as shown in EQ 3:

$$V_{\text{input}} = V_{\text{CCI}} + V_{\text{diode}} = 3.3 \text{ V} + 0.7 \text{ V} = 4.0 \text{ V}$$

EQ 3

The internal VCCI clamp diode is only enabled while the device is powered on, so the voltage at the input will not be clamped if the VCCI or VCCA are powered off. An external series resistor (~100 Ω) is required between the input pin and the 5 V signal source to limit the current to less than 20 mA (Figure 2-3). The 100 Ω resistor was chosen to meet the input Tr/Tf requirement (Table 2-19 on page 2-21). The GND clamp diode is available for all I/O standards and always enabled.

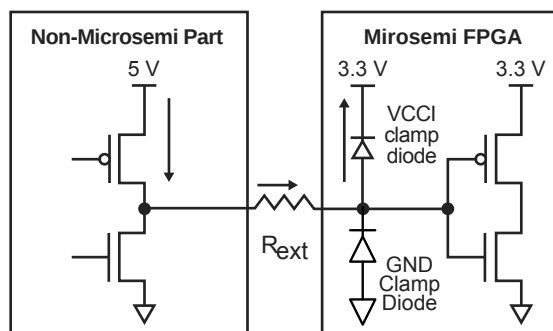


Figure 2-3 • Use of an External Resistor for 5 V Tolerance

2. 5 V tolerance can also be achieved with 3.3 V I/O standards (3.3 V PCI, 3.3 V PCI-X, and LVTTTL) using a bus-switch product (e.g. IDTQS32X2384). This will convert the 5 V signal to a 3.3 V signal with minimum delay (Figure 2-4).

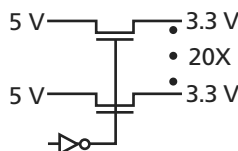


Figure 2-4 • Bus Switch IDTQS32X2384

Simultaneous Switching Outputs (SSO)

When multiple output drivers switch simultaneously, they induce a voltage drop in the chip/package power distribution. This simultaneous switching momentarily raises the ground voltage within the device relative to the system ground. This apparent shift in the ground potential to a non-zero value is known as simultaneous switching noise (SSN) or more commonly, ground bounce.

SSN becomes more of an issue in high pin count packages and when using high performance devices such as the Axcelerator family. Based upon testing, Microsemi recommends that users not exceed eight simultaneous switching outputs (SSO) per each VCCI/GND pair. To ease this potential burden on designers, Microsemi has designed all of the Axcelerator BGAs³ to not exceed this limit with the exception of the CS180, which has an I/O to VCCI/GND pair ratio of nine to one.

Please refer to the *Simultaneous Switching Noise and Signal Integrity* application note for more information.

3. The user should note that in Bank 8 of both AX1000-FG484 and AX500-FG484, there are local violations of this 8:1 ratio.

Timing Characteristics

Table 2-22 • 3.3 V LVTTTL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_j = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTTL Output Drive Strength = 1 (8 mA) / Low Slew Rate								
t _{DP}	Input Buffer		1.68		1.92		2.26	ns
t _{PY}	Output Buffer		14.28		16.27		19.13	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		15.25		17.37		20.42	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		14.26		16.24		19.09	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.56		1.57		1.58	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		1.95		1.96		1.97	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-69 • AX2000 Predicted Routing Delays
Worst-Case Commercial Conditions VCCA = 1.425 V, T_J = 70°C

		-2 Speed	-1 Speed	Std Speed	
Parameter	Description	Typical	Typical	Typical	Units
Predicted Routing Delays					
t _{DC}	DirectConnect Routing Delay, FO1	0.12	0.13	0.15	ns
t _{FC}	FastConnect Routing Delay, FO1	0.35	0.39	0.46	ns
t _{RD1}	Routing delay for FO1	0.50	0.56	0.66	ns
t _{RD2}	Routing delay for FO2	0.59	0.67	0.79	ns
t _{RD3}	Routing delay for FO3	0.70	0.80	0.94	ns
t _{RD4}	Routing delay for FO4	0.76	0.87	1.02	ns
t _{RD5}	Routing delay for FO5	0.98	1.11	1.31	ns
t _{RD6}	Routing delay for FO6	1.48	1.68	1.97	ns
t _{RD7}	Routing delay for FO7	1.65	1.87	2.20	ns
t _{RD8}	Routing delay for FO8	1.73	1.96	2.31	ns
t _{RD16}	Routing delay for FO16	2.58	2.92	3.44	ns
t _{RD32}	Routing delay for FO32	4.24	4.81	5.65	ns

Table 2-83 • South PLL Connections

CLK1	CLK2
CLK1	Routed net
CLK1	Unused
CLK2	CLK1
CLK2	Routed net
CLK2	Both CLK1 and routed net
CLK2	Unused
Unused	CLK1
Unused	Routed net
Unused	Both CLK1 and routed net
Unused	Unused
Routed net	CLK1
Routed net	Unused
Both CLK1 and CLK2	Routed net
Both CLK1 and CLK2	Unused
Both CLK1 and routed net	Unusable
Both CLK2 and routed net	CLK1
Both CLK2 and routed net	Unused
CLK1, CLK2, and routed net	Unusable

Note: Designer software currently does not support all of these connections. Only exclusive connections where one output connects to a single net are supported at this time (e.g., CLK1 driving both CLK1 and CLK2 is not supported).

Special PLL Macros

Table 2-84 shows the macros used to connect the RefCLK input and CLK1 and CLK2 outputs using the different routing resources.

Table 2-84 • PLL Special Macros

Macro Name	Usage
PLLINT	Connects RefCLK to a regular routed net or a pad.
PLLCLK	Connects CLK1 or CLK2 to the CLK network.
PLHCLK	Connects CLK1 or CLK2 to the HCLK network.
PLLOUT	Connects CLK1 or CLK2 to a regular routed net.

Table 2-85 • Electrical Specifications

Parameter	Value	Notes
Frequency Ranges		
Reference Frequency (min.)	14 MHz	Lowest input frequency
Reference Frequency (max.)	200 MHz	Highest input frequency
OSC Frequency (min.)	20 MHz	Lowest output frequency
OSC Frequency (max.)	1 GHz	Highest output frequency
Jitter		
Long-Term Jitter (max.)	1%	Percentage of period, low reference clock frequencies
Long-Term Jitter (max.)	100ps	High reference clock frequencies
Short-Term Jitter (max.)	50ps+1%	Percentage of output frequency
Acquisition Time (lock) from Cold Start		
Acquisition Time (max.)*	400 cycles	Period of low reference clock frequencies
Acquisition Time (max.)*	1.5 μ s	High reference clock frequencies
Power Consumption		
Analog Supply Current (low freq.)	200 μ A	Current at minimum oscillator frequency
Analog Supply Current (high freq.)	200 μ A	Frequency-dependent current
Digital Supply Current (low freq.)	0.5 μ A/MHz	Current at maximum oscillator frequency, unloaded
Digital Supply Current (high freq.)	1 μ A/MHz	Frequency-dependent current
Duty Cycle		
Minimum Output Duty Cycle	45%	
Maximum Output Duty Cycle	55%	

Note: *The lock bit remains Low until RefCLK reaches the minimum input frequency.

Timing Characteristics

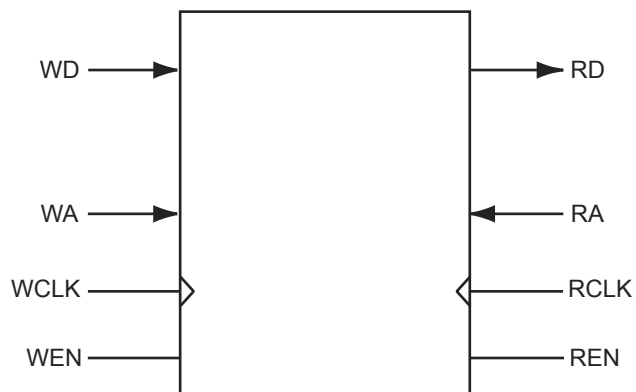


Figure 2-58 • SRAM Model

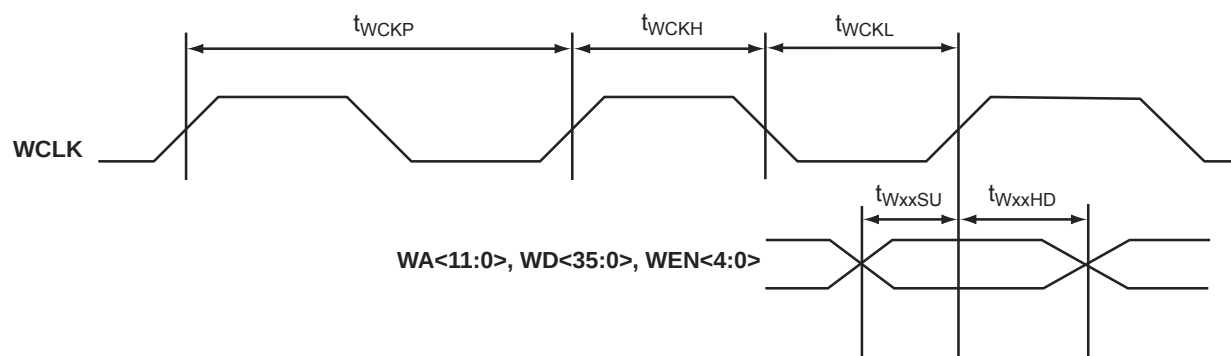


Figure 2-59 • RAM Write Timing Waveforms

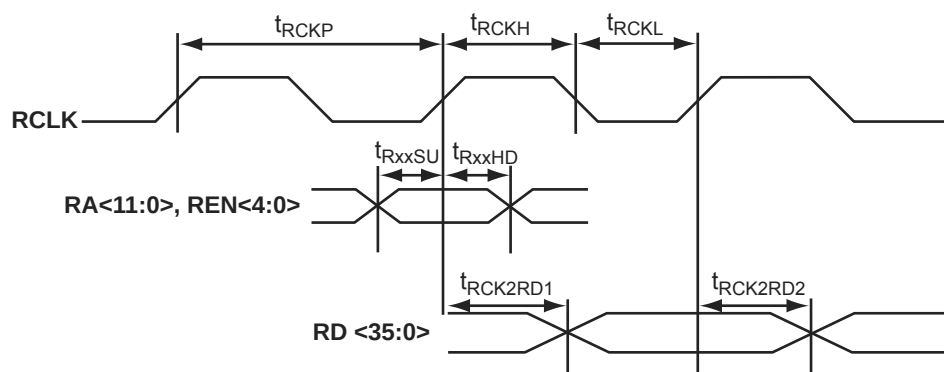


Figure 2-60 • RAM Read Timing Waveforms

Figure 2-63 illustrates flag generation.

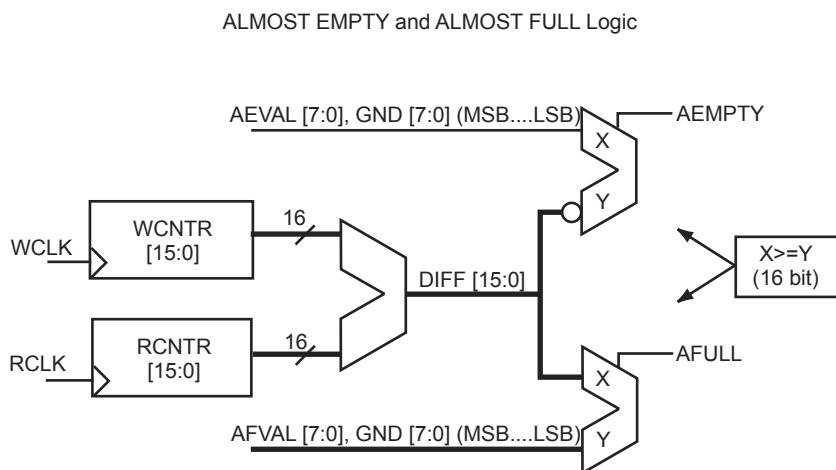


Figure 2-63 • ALMOST-EMPTY and ALMOST-FULL Logic

The Verilog codes for the flags are:

```
assign AF = (DIFF[15:0] >={AFVAL[7:0], 8'b00000000})?1:0;
assign AE = ({AEVAL[7:0], 8'b00000000} >=DIFF[15:0])?1:0;
```

The number of DIFF-bits active depends on the configuration depth and width (Table 2-95).

Table 2-95 • Number of Available Configuration Bits

Number of Blocks	Block DxW	Number of AEVAL/AFVAL Bits
1	1x1	4
2	1x2	4
2	2x1	5
4	1x4	4
4	2x2	5
4	4x1	6
8	1x8	4
8	2x4	5
8	4x2	6
8	8x1	7
16	1x16	4
16	2x8	5
16	4x4	6
16	8x2	7
16	16x1	8

The active-high CLR pin is used to reset the FIFO to the empty state, which sets FULL and AFULL low, and EMPTY and AEMPTY high.

Assuming that the EMPTY flag is not set, new data is read from the FIFO when REN is valid on the active edge of the clock. Write and read transfers are described with timing requirements in "Timing Characteristics" on page 2-100.

FG324	
AX125 Function	Pin Number
Bank 0	
IO00NB0F0	C5
IO00PB0F0	C4
IO01NB0F0	A3
IO01PB0F0	A2
IO02NB0F0	C7
IO02PB0F0	C6
IO03NB0F0	B5
IO03PB0F0	B4
IO04NB0F0	A5
IO04PB0F0	A4
IO05NB0F0	A7
IO05PB0F0	A6
IO06NB0F0	B7
IO06PB0F0	B6
IO07NB0F0/HCLKAN	C9
IO07PB0F0/HCLKAP	C8
IO08NB0F0/HCLKBN	B10
IO08PB0F0/HCLKBP	B9
Bank 1	
IO09NB1F1/HCLKCN	D11
IO09PB1F1/HCLKCP	D10
IO10NB1F1/HCLKDN	C12
IO10PB1F1/HCLKDP	C11
IO11NB1F1	A15
IO11PB1F1	A14
IO12NB1F1	B14
IO12PB1F1	B13
IO13NB1F1	A17
IO13PB1F1	A16
IO14NB1F1	D13
IO14PB1F1	D12
IO15NB1F1	C14
IO15PB1F1	C13
IO16NB1F1	B16

FG324	
AX125 Function	Pin Number
IO16PB1F1	C15
IO17NB1F1	E14
IO17PB1F1	E13
Bank 2	
IO18NB2F2	G14
IO18PB2F2	F14
IO19NB2F2	D16
IO19PB2F2	D15
IO20NB2F2	C18
IO20PB2F2	B18
IO21NB2F2	D17
IO21PB2F2	C17
IO22NB2F2	F17
IO22PB2F2	E17
IO23NB2F2	G16
IO23PB2F2	F16
IO24NB2F2	E18
IO24PB2F2	D18
IO25NB2F2	G18
IO25PB2F2	F18
IO26NB2F2	H17
IO26PB2F2	G17
IO27NB2F2	J16
IO27PB2F2	H16
IO28NB2F2	J18
IO28PB2F2	H18
IO29NB2F2	K17
IO29PB2F2	J17
Bank 3	
IO30NB3F3	N18
IO30PB3F3	M18
IO31NB3F3	L18
IO31PB3F3	K18
IO32NB3F3	L16
IO32PB3F3	L17

FG324	
AX125 Function	Pin Number
IO33NB3F3	R18
IO33PB3F3	P18
IO34NB3F3	N15
IO34PB3F3	M15
IO35NB3F3	M16
IO35PB3F3	M17
IO36NB3F3	P16
IO36PB3F3	N16
IO37NB3F3	R17
IO37PB3F3	P17
IO38NB3F3	N14
IO38PB3F3	M14
IO39NB3F3	U18
IO39PB3F3	T18
IO40NB3F3	R16
IO40PB3F3	T17
IO41NB3F3	P13
IO41PB3F3	P14
Bank 4	
IO42NB4F4	T13
IO42PB4F4	T14
IO43NB4F4	U15
IO43PB4F4	T15
IO44NB4F4	U13
IO44PB4F4	U14
IO45NB4F4	V15
IO45PB4F4	V16
IO46NB4F4	V13
IO46PB4F4	V14
IO47NB4F4	V12
IO47PB4F4	U12
IO48NB4F4	V10
IO48PB4F4	V11
IO49NB4F4/CLKEN	T10
IO49PB4F4/CLKEP	T11

FG324		FG324		FG324	
AX125 Function	Pin Number	AX125 Function	Pin Number	AX125 Function	Pin Number
GND	R4	NC	N4	VCCA	M8
GND	T16	NC	N5	VCCA	M9
GND	T3	NC	R12	VCCA	P4
GND	U17	NC	R13	VCCA	R15
GND	U2	NC	R6	VCCPLA	D8
GND	V1	NC	R7	VCCPLB	E7
GND	V18	NC	T12	VCCPLC	B11
GND/LP	E5	NC	T6	VCCPLD	E11
NC	A10	NC	U16	VCCPLE	R11
NC	A11	NC	V17	VCCPLF	P12
NC	A12	PRA	E9	VCCPLG	U8
NC	A13	PRB	D9	VCCPLH	P8
NC	A8	PRC	P10	VCCDA	B3
NC	A9	PRD	R10	VCCDA	D14
NC	B12	TCK	E6	VCCDA	E10
NC	F15	TDI	D7	VCCDA	J2
NC	F4	TDO	D5	VCCDA	K16
NC	G15	TMS	D4	VCCDA	P15
NC	G4	TRST	D6	VCCDA	P9
NC	H14	VCCA	E15	VCCDA	R5
NC	H15	VCCA	G10	VCCIB0	F7
NC	H5	VCCA	G11	VCCIB0	F8
NC	J1	VCCA	G5	VCCIB0	F9
NC	J14	VCCA	G8	VCCIB1	F10
NC	J15	VCCA	G9	VCCIB1	F11
NC	J5	VCCA	H12	VCCIB1	F12
NC	K14	VCCA	H7	VCCIB2	G13
NC	K15	VCCA	J12	VCCIB2	H13
NC	K5	VCCA	J7	VCCIB2	J13
NC	L14	VCCA	K12	VCCIB3	K13
NC	L15	VCCA	K7	VCCIB3	L13
NC	L5	VCCA	L12	VCCIB3	M13
NC	M4	VCCA	L7	VCCIB4	N10
NC	M5	VCCA	M10	VCCIB4	N11
NC	N17	VCCA	M11	VCCIB4	N12

FG676		FG676		FG676	
AX500 Function	Pin Number	AX500 Function	Pin Number	AX500 Function	Pin Number
IO51NB2F4	L20	IO68NB3F6	V26	IO85NB4F8	AE23
IO51PB2F4	L21	IO68PB3F6	U26	IO85PB4F8	AE24
IO52NB2F5	K26	IO69NB3F6	V25	IO86NB4F8	AC21
IO52PB2F5	J26	IO69PB3F6	U25	IO86PB4F8	AC22
IO53NB2F5	L23	IO70NB3F6	Y25	IO87NB4F8	AF22
IO53PB2F5	L22	IO70PB3F6	W25	IO87PB4F8	AF23
IO54NB2F5	L24	IO71NB3F6	W24	IO88NB4F8	AD22
IO54PB2F5	K24	IO71PB3F6	V24	IO88PB4F8	AD23
IO55NB2F5	M20	IO72NB3F6	V23	IO89NB4F8	AC19
IO55PB2F5	M21	IO72PB3F6	U23	IO89PB4F8	AC20
IO56NB2F5	L26	IO73NB3F6	T21	IO90NB4F8	AE21
IO56PB2F5	L25	IO73PB3F6	T20	IO90PB4F8	AE22
IO57NB2F5	M23	IO74NB3F7	AA26	IO91NB4F8	AA17
IO57PB2F5	M22	IO74PB3F7	Y26	IO91PB4F8	AA18
IO58NB2F5	M26	IO75NB3F7	AA24	IO92NB4F8	AD20
IO58PB2F5	M25	IO75PB3F7	Y24	IO92PB4F8	AD21
IO59NB2F5	N22	IO76NB3F7	Y23	IO93NB4F8	AF20
IO59PB2F5	N23	IO76PB3F7	W23	IO93PB4F8	AF21
IO60NB2F5	N24	IO77NB3F7	V21	IO94NB4F9	AE19
IO60PB2F5	M24	IO77PB3F7	U21	IO94PB4F9	AE20
IO61NB2F5	N20	IO78NB3F7	AB25	IO95NB4F9	AC17
IO61PB2F5	N21	IO78PB3F7	AA25	IO95PB4F9	AC18
IO62NB2F5	P25	IO79NB3F7	AC26	IO96NB4F9	AD18
IO62PB2F5	N25	IO79PB3F7	AB26	IO96PB4F9	AD19
Bank 3		IO80NB3F7	AC24	IO97NB4F9	AA16
IO63NB3F6	T26	IO80PB3F7	AB24	IO97PB4F9	Y16
IO63PB3F6	R26	IO81NB3F7	AB23	IO98NB4F9	AE17
IO64NB3F6	R24	IO81PB3F7	AA23	IO98PB4F9	AE18
IO64PB3F6	P24	IO82NB3F7	AA22	IO99NB4F9	AC16
IO65NB3F6	P20	IO82PB3F7	Y22	IO99PB4F9	AB16
IO65PB3F6	P21	IO83NB3F7	AE26	IO100NB4F9	AF17
IO66NB3F6	T25	IO83PB3F7	AD26	IO100PB4F9	AF18
IO66PB3F6	R25	Bank 4		IO101NB4F9	AA15
IO67NB3F6	T23	IO84NB4F8	AB21	IO101PB4F9	Y15
IO67PB3F6	R23	IO84PB4F8	AA21	IO102NB4F9	AC15

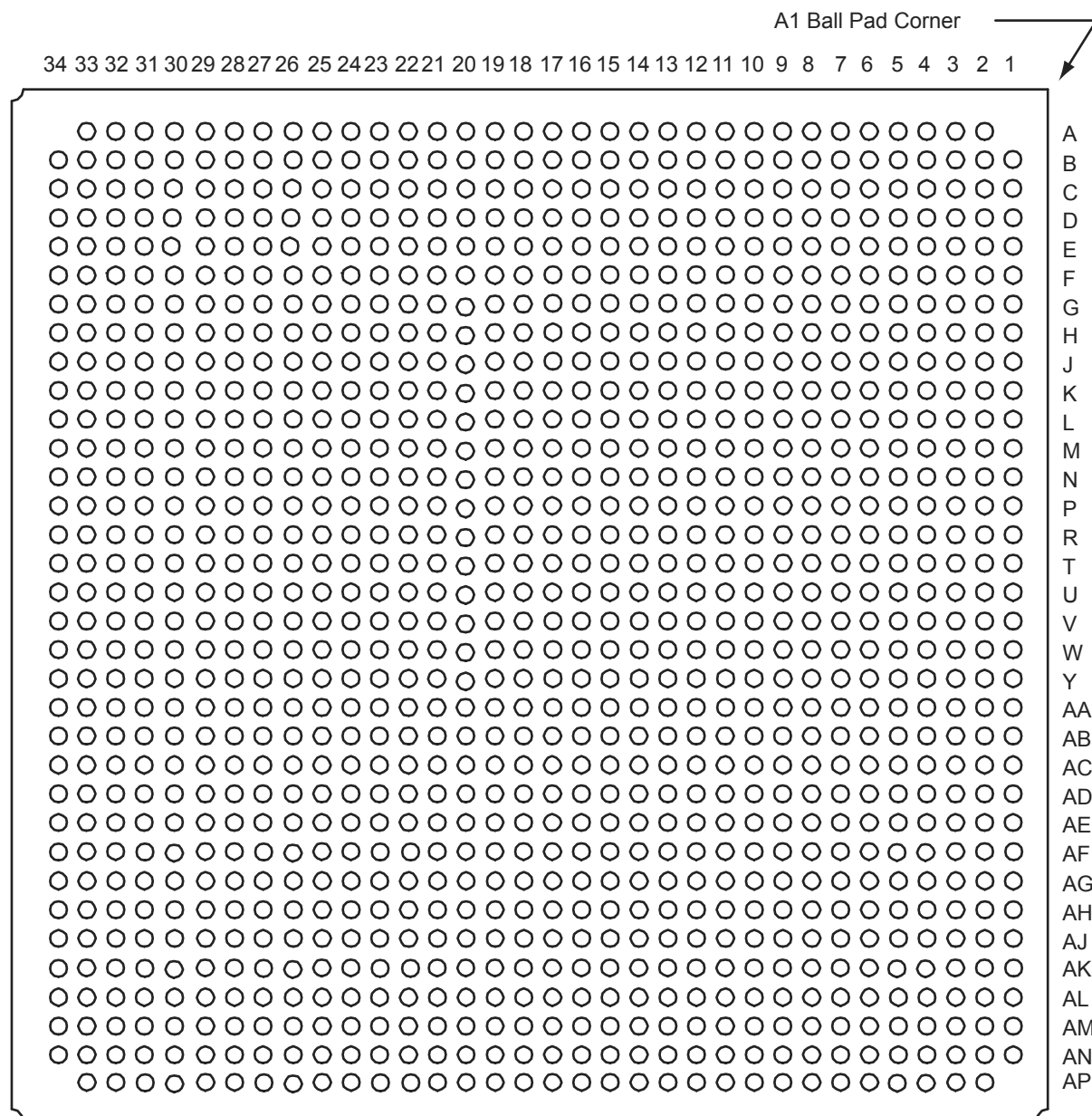
FG676	
AX500 Function	Pin Number
GND	R10
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A11
NC	A21

FG676	
AX500 Function	Pin Number
NC	A22
NC	A24
NC	A25
NC	AA11
NC	AA19
NC	AA20
NC	AA4
NC	AA5
NC	AA6
NC	AA7
NC	AA8
NC	AA9
NC	AB1
NC	AB11
NC	AB17
NC	AB18
NC	AB19
NC	AB20
NC	AB8
NC	AB9
NC	AC1
NC	AC13
NC	AC14
NC	AC25
NC	AD1
NC	AD11
NC	AD16
NC	AD25
NC	AE1
NC	AF2
NC	AF25
NC	B11
NC	B24
NC	B4
NC	C16

FG676	
AX500 Function	Pin Number
NC	C4
NC	D1
NC	D13
NC	D14
NC	D17
NC	D18
NC	D2
NC	D26
NC	D3
NC	D9
NC	E1
NC	E18
NC	E23
NC	E24
NC	E26
NC	E3
NC	E4
NC	E9
NC	F1
NC	F18
NC	F20
NC	F21
NC	F22
NC	F23
NC	F24
NC	F4
NC	F6
NC	F7
NC	G21
NC	G22
NC	H21
NC	H22
NC	H23
NC	H5
NC	H6

FG896		FG896		FG896	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO51PB1F4	E21	IO68PB2F6	K24	IO86NB2F8	N28
IO52NB1F4	F22	IO69NB2F6	F27	IO86PB2F8	N27
IO52PB1F4	E22	IO69PB2F6	E27	IO87NB2F8	P29
IO53NB1F4	B25	IO70NB2F6	J26	IO87PB2F8	P30
IO53PB1F4	B24	IO70PB2F6	J25	IO88NB2F8	P25
IO54NB1F5	D24	IO71NB2F6	H27	IO88PB2F8	P24
IO54PB1F5	D23	IO71PB2F6	G27	IO89NB2F8	P28
IO55NB1F5	F23	IO72NB2F6	J28	IO89PB2F8	P27
IO55PB1F5	E23	IO72PB2F6	H28	IO90NB2F8	P22
IO56NB1F5	H21	IO73NB2F6	G28	IO90PB2F8	P23
IO56PB1F5	G21	IO73PB2F6	F28	IO91NB2F8	R26
IO57NB1F5	D25	IO74NB2F7	L23	IO91PB2F8	P26
IO57PB1F5	C25	IO74PB2F7	L24	IO92NB2F8	R24
IO58NB1F5	F24	IO75NB2F7	L26	IO92PB2F8	R25
IO58PB1F5	E24	IO75PB2F7	K26	IO93NB2F8	R29
IO59NB1F5	D26	IO76NB2F7	M25	IO93PB2F8	R30
IO59PB1F5	C26	IO76PB2F7	L25	IO94NB2F8	R22
IO60NB1F5	G23	IO77NB2F7	K27	IO94PB2F8	R23
IO60PB1F5	G22	IO77PB2F7	J27	IO95NB2F8	T27
IO61NB1F5	B27	IO78NB2F7	M27	IO95PB2F8	R27
IO61PB1F5	A27	IO78PB2F7	L27	Bank 3	
IO62NB1F5	F25	IO79NB2F7	K30	IO96NB3F9	T29
IO62PB1F5	E25	IO79PB2F7	K29	IO96PB3F9	T30
IO63NB1F5	H23	IO80NB2F7	M23	IO97NB3F9	U29
IO63PB1F5	H22	IO80PB2F7	M24	IO97PB3F9	U30
Bank 2		IO81NB2F7	M28	IO98NB3F9	T22
IO64NB2F6	K23	IO81PB2F7	L28	IO98PB3F9	T23
IO64PB2F6	J23	IO82NB2F7	N26	IO99NB3F9	U26
IO65NB2F6	J24	IO82PB2F7	M26	IO99PB3F9	T26
IO65PB2F6	H24	IO83NB2F7	N25	IO100NB3F9	U24
IO66NB2F6	H26	IO83PB2F7	N24	IO100PB3F9	T24
IO66PB2F6	H25	IO84NB2F7	N22	IO101NB3F9	V28
IO67NB2F6	G26	IO84PB2F7	N23	IO101PB3F9	U28
IO67PB2F6	G25	IO85NB2F8	M29	IO102NB3F9	U23
IO68NB2F6	K25	IO85PB2F8	L29	IO102PB3F9	U22

FG1152



Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.microsemi.com/soc/products/rescenter/package/index.html>.

CQ352		CQ352		CQ352	
AX500 Function	Pin Number	AX500 Function	Pin Number	AX500 Function	Pin Number
GND	21	GND	240	TDI	348
GND	27	GND	246	TDO	347
GND	33	GND	252	TMS	350
GND	39	GND	258	TRST	351
GND	45	GND	264	VCCA	3
GND	51	GND	265	VCCA	14
GND	57	GND	274	VCCA	32
GND	63	GND	280	VCCA	56
GND	69	GND	286	VCCA	74
GND	75	GND	292	VCCA	87
GND	81	GND	298	VCCA	102
GND	88	GND	310	VCCA	114
GND	89	GND	322	VCCA	150
GND	97	GND	330	VCCA	162
GND	103	GND	334	VCCA	175
GND	109	GND	340	VCCA	191
GND	115	GND	345	VCCA	209
GND	121	GND/LP	352	VCCA	233
GND	133	NC	91	VCCA	251
GND	145	NC	117	VCCA	263
GND	151	NC	130	VCCA	279
GND	157	NC	131	VCCA	291
GND	163	NC	148	VCCA	329
GND	169	NC	174	VCCA	339
GND	176	NC	268	VCCDA	2
GND	177	NC	294	VCCDA	44
GND	186	NC	307	VCCDA	90
GND	192	NC	308	VCCDA	116
GND	198	NC	327	VCCDA	132
GND	204	NC	328	VCCDA	149
GND	210	PRA	312	VCCDA	178
GND	216	PRB	311	VCCDA	221
GND	222	PRC	135	VCCDA	266
GND	228	PRD	134	VCCDA	293
GND	234	TCK	349	VCCDA	309

CG624		CG624		CG624	
AX1000 Function	Pin Number	AX1000 Function	Pin Number	AX1000 Function	Pin Number
IO63PB1F5	G18	IO84NB2F7	M20	IO105NB3F9	R23
Bank 2		IO84PB2F7	M21	IO105PB3F9	P23
IO64NB2F6	M17	IO86NB2F8	E25	IO106NB3F9	R19
IO64PB2F6	G22	IO86PB2F8	D25	IO106PB3F9	R20
IO65NB2F6	J21	IO87NB2F8	L24	IO107NB3F10	AB24
IO65PB2F6	J20	IO87PB2F8	K24	IO108NB3F10	R25
IO66NB2F6	L23	IO88NB2F8	G24	IO108PB3F10	P25
IO66PB2F6	K20	IO88PB2F8	F24	IO109NB3F10	U25
IO67NB2F6	F23	IO89NB2F8	J25	IO109PB3F10	T25
IO67PB2F6	E23	IO90NB2F8	G25	IO110NB3F10	U24
IO68NB2F6	L18	IO90PB2F8	F25	IO110PB3F10	U23
IO68PB2F6	K18	IO91NB2F8	L25	IO112NB3F10	T24
IO70NB2F6	E24	IO91PB2F8	K25	IO112PB3F10	R24
IO70PB2F6	D24	IO92NB2F8	J24	IO113NB3F10	Y25
IO71NB2F6	H23	IO92PB2F8	H24	IO113PB3F10	W25
IO71PB2F6	G23	IO93PB2F8	J23	IO114NB3F10	V23
IO72NB2F6	L19	IO94NB2F8	N24	IO114PB3F10	V24
IO72PB2F6	K19	IO94PB2F8	M24	IO116NB3F10	AA24
IO74NB2F7	J22	IO95NB2F8	N25	IO116PB3F10	Y24
IO74PB2F7	H22	IO95PB2F8	M25	IO117NB3F10	AB25
IO75NB2F7	N23	Bank 3		IO117PB3F10	AA25
IO75PB2F7	M23	IO96NB3F9	T18	IO118NB3F11	T20
IO76NB2F7	N17	IO96PB3F9	R18	IO118PB3F11	R21
IO76PB2F7	N16	IO97NB3F9	N20	IO120NB3F11	W22
IO77NB2F7	L22	IO97PB3F9	P24	IO120PB3F11	W23
IO77PB2F7	K22	IO98NB3F9	P20	IO122NB3F11	V22
IO78NB2F7	M19	IO98PB3F9	P19	IO122PB3F11	U22
IO78PB2F7	M18	IO99NB3F9	P21	IO124NB3F11	Y23
IO79NB2F7	N19	IO100NB3F9	T22	IO124PB3F11	AA23
IO79PB2F7	N18	IO100PB3F9	W24	IO126NB3F11	V21
IO80NB2F7	L21	IO101NB3F9	R22	IO126PB3F11	U21
IO80PB2F7	L20	IO101PB3F9	P22	IO128NB3F11	Y22
IO82NB2F7	P18	IO102NB3F9	U19	IO128PB3F11	Y21
IO82PB2F7	P17	IO102PB3F9	T19	Bank 4	
IO83NB2F7	N22	IO104NB3F9	V20	IO129NB4F12	W20
IO83PB2F7	M22	IO104PB3F9	U20	IO129PB4F12	Y20

CG624	
AX2000 Function	Pin Number
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	R11
GND	R12
GND	R13
GND	R14
GND	R15
GND	T21
GND	T23
GND	T3
GND	T5
GND	V1
GND	V25
GND	V5
PRA	F13
PRB	A13
PRC	AB12
PRD	AE13
TCK	F5

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
TDI	C5
TDO	F6
TMS	D6
TRST	E6
VCCA	AB20
VCCA	F22
VCCA	F4
VCCA	J17
VCCA	J9
VCCA	K10
VCCA	K11
VCCA	K15
VCCA	K16
VCCA	L10
VCCA	L16
VCCA	R10
VCCA	R16
VCCA	T10
VCCA	T11
VCCA	T15
VCCA	T16
VCCA	U17
VCCA	U9
VCCA	Y4
VCCDA	A12
VCCDA	A14
VCCDA	AA13
VCCDA	AA15
VCCDA	AA20
VCCDA	AA7
VCCDA	AB13
VCCDA	AC11

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
VCCDA	AD11
VCCDA	AD4
VCCDA	AE12
VCCDA	AE17
VCCDA	B15
VCCDA	C15
VCCDA	C6
VCCDA	D13
VCCDA	E13
VCCDA	E19
VCCDA	F21
VCCDA	G10
VCCDA	G5
VCCDA	N21
VCCDA	N5
VCCDA	W21
VCCIB0	A3
VCCIB0	B3
VCCIB0	C4
VCCIB0	D5
VCCIB0	J10
VCCIB0	J11
VCCIB0	K12
VCCIB1	A23
VCCIB1	B23
VCCIB1	C22
VCCIB1	D21
VCCIB1	J15
VCCIB1	J16
VCCIB1	K14
VCCIB2	C24
VCCIB2	C25

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.